

SOT1459-1

wafer level chip-scale package; 42 bumps; 2.88 mm x 2.80 mm x 0.54 mm (Backside coating included)

15 November 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP42
Package type industry code	WLCSP
Package style descriptive code	WLCSP
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	1-9-2016
Manufacturer package code	SOT1459

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.86	-	2.88	2.9	mm
E	package width	2.78	-	2.8	2.82	mm
A	seated height	0.5	-	0.54	0.58	mm
A ₂	package height	0.31	-	0.34	0.37	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	42	-	



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2. Package outline

WLCSP42: wafer level chip-scale package; 42 bumps; 2.88 x 2.80 x 0.54 mm (Backside coating included) SOT1459-1

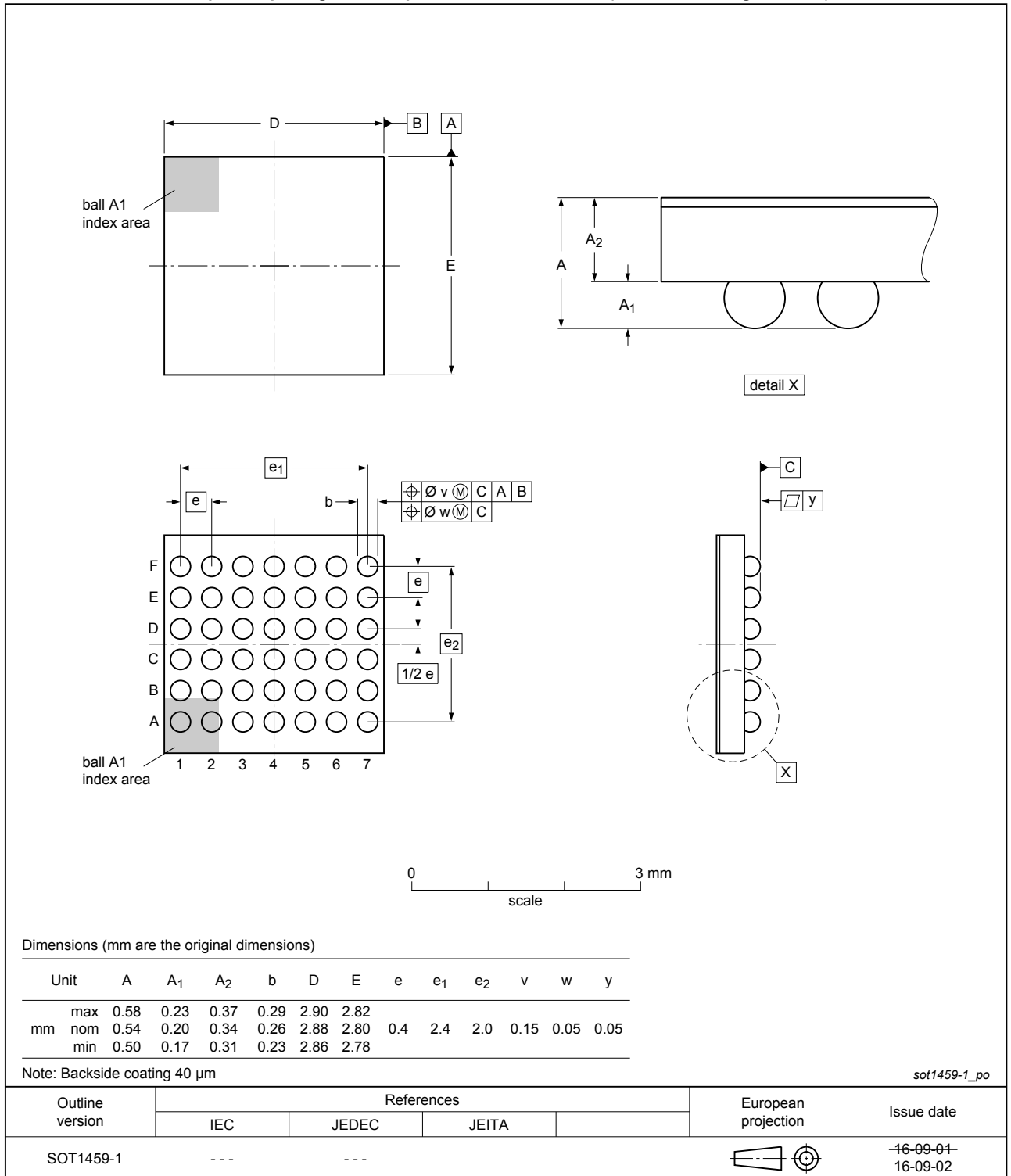


Fig. 1. Package outline WLCSP (SOT1459-1)

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3. Legal information

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Date of release: 15 November 2016
